## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

OR:

HWANG ET AL.

FRIAL NO.: 10/022,349

December 20, 2001

GROUP ART UNIT: 2814

EXAMINER: D. WILLIE

0 3 2003

A SINGLE-CHIP STRUCTURE OF SILICON GERMANIUM PHOTODETECTOR AND HIGH-

ATTY. REFERENCE: HWAN3013/EM

SPEED TRANSISTOR

COMMISSIONER OF PATENTS

P.O. Box 1450

**Alexandria, VA 22313-1450** 

Sir:

Transmitted herewith is a communication/amendment in the above-identified application.

Small entity status under 37 CFR 1.9 and 1.27 is claimed.

 $\boxtimes$ No additional fee is required.

The fee, if any, has been calculated as shown below:

Fee Basis	Number of Claims After Amendment	Highest Number Previously Paid For	Extra Claims	\$ 100 mm and 100 mm an	Full Fee	
Total Claims	20	- 20	= 0	× \$ 9 =	× \$ 18 =	\$0.00
Independent Claims	2	- 3	= 0	× \$ 42 =	× \$ 84 =	\$0.00
☐ First Presentation of Proper Multiple Dependent Claim				+ \$140 =	+ \$280 =	
			TOTAL		\$0.00	••

<sup>&</sup>lt;sup>1</sup> If less than 20 enter 20.

	is attached. A duplicate copy of this sheet
	A check in the amount of _\$ is attached.
×	The Commissioner is hereby authorized to charge any additional fees associated with this communication, including fees due under 37 CFR 1.16 and 37 CFR 1.17 or credit any overpayment to Deposit Account Number 02-0200. A duplicate copy of this sheet is attached.
	Also enclosed is/are:

**BACON & THOMAS, PLLC** 625 SLATERS LANE - FOURTH FLOOR ALEXANDRIA, VIRGINIA 223124-1176 (703) 683-0500

PATENT TRADEMARK OFFICE

DATE: June 3, 2003 Respectfully submitted,

Richard E. Fichter Attorney for Applicant

Registration Number: 26,382

<sup>&</sup>lt;sup>2</sup> If less than 3 enter 3.

<sup>&</sup>lt;sup>3</sup> If less than 0 enter 0.

**PATENT** 



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814

Examiner: D. Wille

e Application of:

HWANG et al.

Serial No.: 10/022,349

Filed: December 20, 2001

For: A SINGLE-CHIP STRUCTURE OF SILICON GERMANIUM

PHOTODETECTOR AND HIGH-SPEED TRANSISTOR

**AMENDMENT** 

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

This is in response to the Official Action of March 3, 2003, in connection with the above-identified application.

Please amend the above-identified application as follows.

## IN THE CLAIMS:

Please add the following new claims to the application.

37(New). A single-chip structure of silicon germanium photodetectors and high-speed transistors according to claim 20 wherein the insulation layer is perpendicular to and touches the substrate and goes through the base layer, photoabsorbing and collector layers.

38(New). A single-chip structure of silicon germanium photodetectors and high-speed transistors according to claim 29 wherein the insulation layer is perpendicular to and touches the substrate and goes through the base layer, photoabsorbing and collector layers.

MUSHU S JUN-4 2003
TECHNOLOGY CENTER 2800